

## 54LS10/DM54LS10/DM74LS10 Triple 3-Input NAND Gates

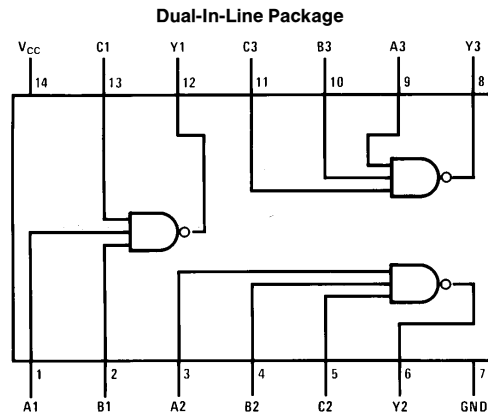
### General Description

This device contains three independent gates each of which performs the logic NAND function.

### Features

- Alternate Military/Aerospace device (54LS10) is available. Contact a National Semiconductor Sales Office/Distributor for specifications.

### Connection Diagram



TL/F/6349-1

Order Number 54LS10DMQB, 54LS10FMQB, 54LS10LMQB,  
DM54LS10J, DM54LS10W, DM74LS10M or DM74LS10N  
See NS Package Number E20A, J14A, M14A, N14A or W14B

### Function Table

$$Y = \overline{ABC}$$

Inputs			Output
A	B	C	Y
X	X	L	H
X	L	X	H
L	X	X	H
H	H	H	L

H = High Logic Level

L = Low Logic Level

X = Either Low or High Logic Level

## Absolute Maximum Ratings (Note)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage	7V
Input Voltage	7V
Operating Free Air Temperature Range	
DM54LS and 54LS	–55°C to +125°C
DM74LS	0°C to +70°C
Storage Temperature Range	–65°C to +150°C

Note: The “Absolute Maximum Ratings” are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the “Electrical Characteristics” table are not guaranteed at the absolute maximum ratings. The “Recommended Operating Conditions” table will define the conditions for actual device operation.

## Recommended Operating Conditions

Symbol	Parameter	DM54LS10			DM74LS10			Units
		Min	Nom	Max	Min	Nom	Max	
V <sub>CC</sub>	Supply Voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub>	High Level Input Voltage	2			2			V
V <sub>IL</sub>	Low Level Input Voltage			0.7			0.8	V
I <sub>OH</sub>	High Level Output Current			–0.4			–0.4	mA
I <sub>OL</sub>	Low Level Output Current			4			8	mA
T <sub>A</sub>	Free Air Operating Temperature	–55		125	0		70	°C

## Electrical Characteristics over recommended operating free air temperature range (unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ (Note 1)	Max	Units
V <sub>I</sub>	Input Clamp Voltage	V <sub>CC</sub> = Min, I <sub>I</sub> = –18 mA			–1.5	V
V <sub>OH</sub>	High Level Output Voltage	V <sub>CC</sub> = Min, I <sub>OH</sub> = Max, V <sub>IL</sub> = Max	DM54 2.5	3.4		V
V <sub>OL</sub>	Low Level Output Voltage	V <sub>CC</sub> = Min, I <sub>OL</sub> = Max, V <sub>IH</sub> = Min	DM54 0.25	0.25	0.4	V
		I <sub>OL</sub> = 4 mA, V <sub>CC</sub> = Min	DM74 0.35	0.35	0.5	
I <sub>I</sub>	Input Current @ Max Input Voltage	V <sub>CC</sub> = Max, V <sub>I</sub> = 7V			0.1	mA
I <sub>IH</sub>	High Level Input Current	V <sub>CC</sub> = Max, V <sub>I</sub> = 2.7V			20	μA
I <sub>IL</sub>	Low Level Input Current	V <sub>CC</sub> = Max, V <sub>I</sub> = 0.4V			–0.36	mA
I <sub>OS</sub>	Short Circuit Output Current	V <sub>CC</sub> = Max (Note 2)	DM54 –20		–100	mA
			DM74 –20		–100	
I <sub>CCH</sub>	Supply Current with Outputs High	V <sub>CC</sub> = Max		0.6	1.2	mA
I <sub>CCL</sub>	Supply Current with Outputs Low	V <sub>CC</sub> = Max		1.8	3.3	mA

## Switching Characteristics at V<sub>CC</sub> = 5V and T<sub>A</sub> = 25°C (See Section 1 for Test Waveforms and Output Load)

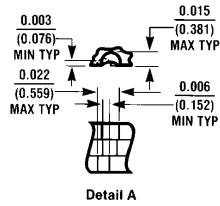
Symbol	Parameter	R <sub>L</sub> = 2 kΩ				Units
		C <sub>L</sub> = 15 pF		C <sub>L</sub> = 50 pF		
		Min	Max	Min	Max	
t <sub>PLH</sub>	Propagation Delay Time Low to High Level Output	3	10	4	15	ns
t <sub>PHL</sub>	Propagation Delay Time High to Low Level Output	3	10	4	15	ns

Note 1: All typicals are at V<sub>CC</sub> = 5V, T<sub>A</sub> = 25°C.

Note 2: Not more than one output should be shorted at a time, and the duration should not exceed one second.

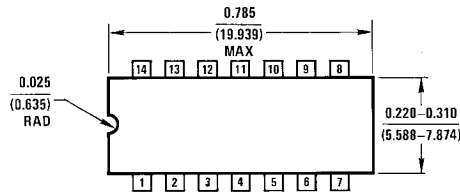


**Physical Dimensions** inches (millimeters)



**Ceramic Leadless Chip Carrier Package (E)**  
 Order Number 54LS10MQB  
 NS Package Number E20A

E20A (REV D)



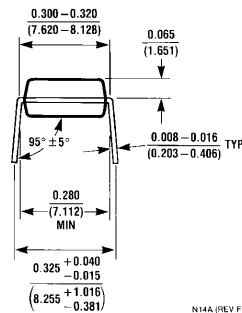
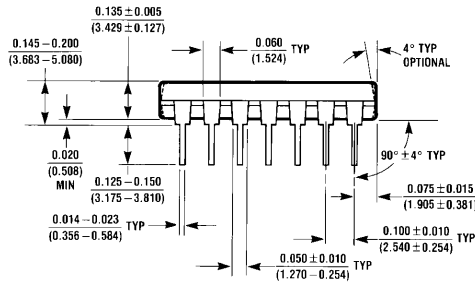
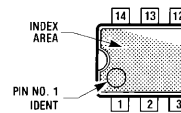
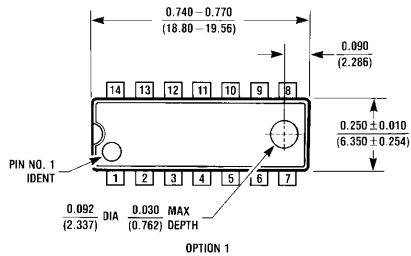
**14-Lead Ceramic Dual-In-Line Package (J)**  
 Order Number 54LS10DMQB or DM54LS10J  
 NS Package Number J14A

J14A (REV G)

**Physical Dimensions** inches (millimeters) (Continued)



**14-Lead Small Outline Molded Package (M)**  
**Order Number DM74LS10M**  
**NS Package Number M14A**



**14-Lead Molded Dual-In-Line Package (N)**  
**Order Number DM74LS10N**  
**NS Package Number N14A**

**Physical Dimensions** inches (millimeters) (Continued)



**14-Lead Ceramic Flat Package (W)**  
**Order Number 54LS10FMQB or DM54LS10W**  
**NS Package Number W14B**

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